

## Driver IC for Lens Motor

# KA41908B Product Brief

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Support for industry standards and quality standards

<b>Functional safety standards for automobiles ISO26262</b>	<b>No</b>
<b>AECQ-100</b>	<b>No</b>
<b>Market failure rate</b>	<b>50Fit</b>

Disclaimer

1. When the application system is designed using this IC, please design the system at your own risk. Please read, consider, and apply appropriate usage notes and description in this standard.
2. When designing your application system, please take into the consideration of break down and failure mode occurrence and possibility in semiconductor products. Measures on the systems such as, but not limited to, redundant design, mitigating the spread of fire, or preventing glitch, are recommended in order to prevent physical injury, fire, social damages, etc. in using the Nuvoton Technology Japan Corporation (hereinafter referred to as NTCJ) products.
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5. This IC does not have any security functions using cryptographic algorithms, such as authentication, encryption, tampering detection.
6. Unless this IC is indicated by NTCJ to be used in applications as meeting the requirements of a particular industry standard (e.g., ISO 9001, IATF 16949, ISO 26262, etc.), this IC is neither designed nor intended for use in such environments for that applications. NTCJ shall not be held responsible for not meeting the requirements of a particular industry standard.
7. Using IC that have been indicated as compliant with industry functional safety standards does not warrant that the application meets the requirements of industry functional safety standards. NTCJ shall not be held responsible for the application compliance with requirements of the particular industry functional safety standard.
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9. In case of damages, costs, losses, and/or liabilities incurred by NTCJ arising from customer's non-compliance with above from 1 to 8, customer will indemnify NTCJ against every damages, costs, losses and responsibility.

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**FEATURES**

- Voltage drive system 256-step microstep drivers (2 systems)
- Motor current amplitude and phase can be adjusted for each channel (CAP (Correction Amplitude & Phase) function)
- Accurate position control of Iris by using Hall sensor and built-in PID control circuit
- Motor control by 4-line serial data communication
- 2 systems of open-drain for driving LED
- Package : QFN 44L (6x6x0.8mm<sup>3</sup>, Lead Pitch 0.4mm)



**DESCRIPTION**

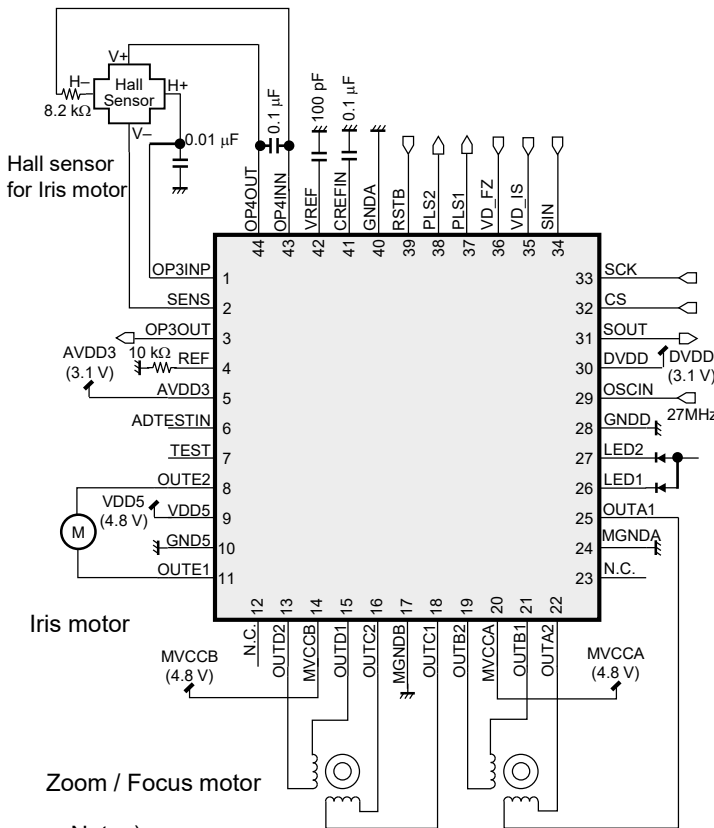
KA41908B is a lens driver IC for surveillance camera and Web camera built-in Iris control. This IC has a built-in iris control function. It realizes low noise microstep drive by adopting voltage drive method, and motor current correction function.

**APPLICATIONS**

- Surveillance camera, Web camera

**TYPICAL APPLICATION**

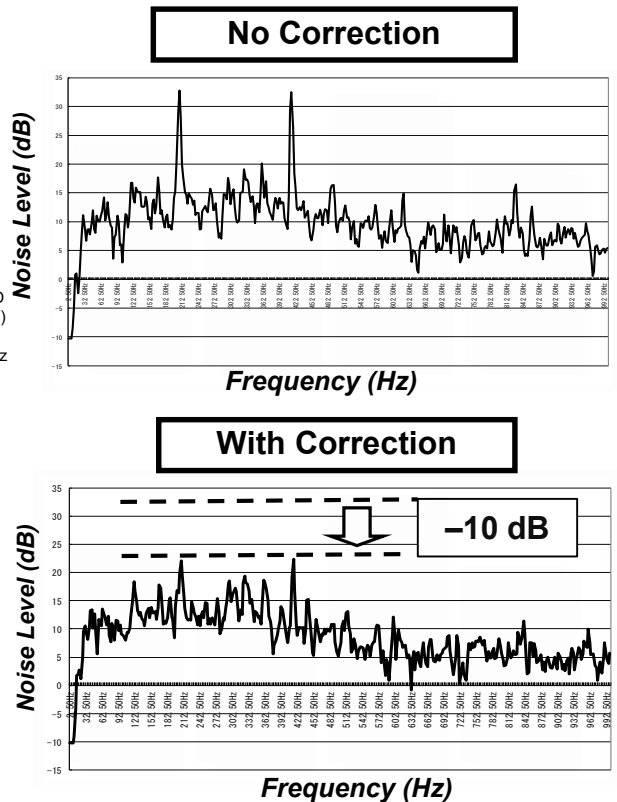
- For Zoom / Focus / Iris motor



**Notes**

This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.

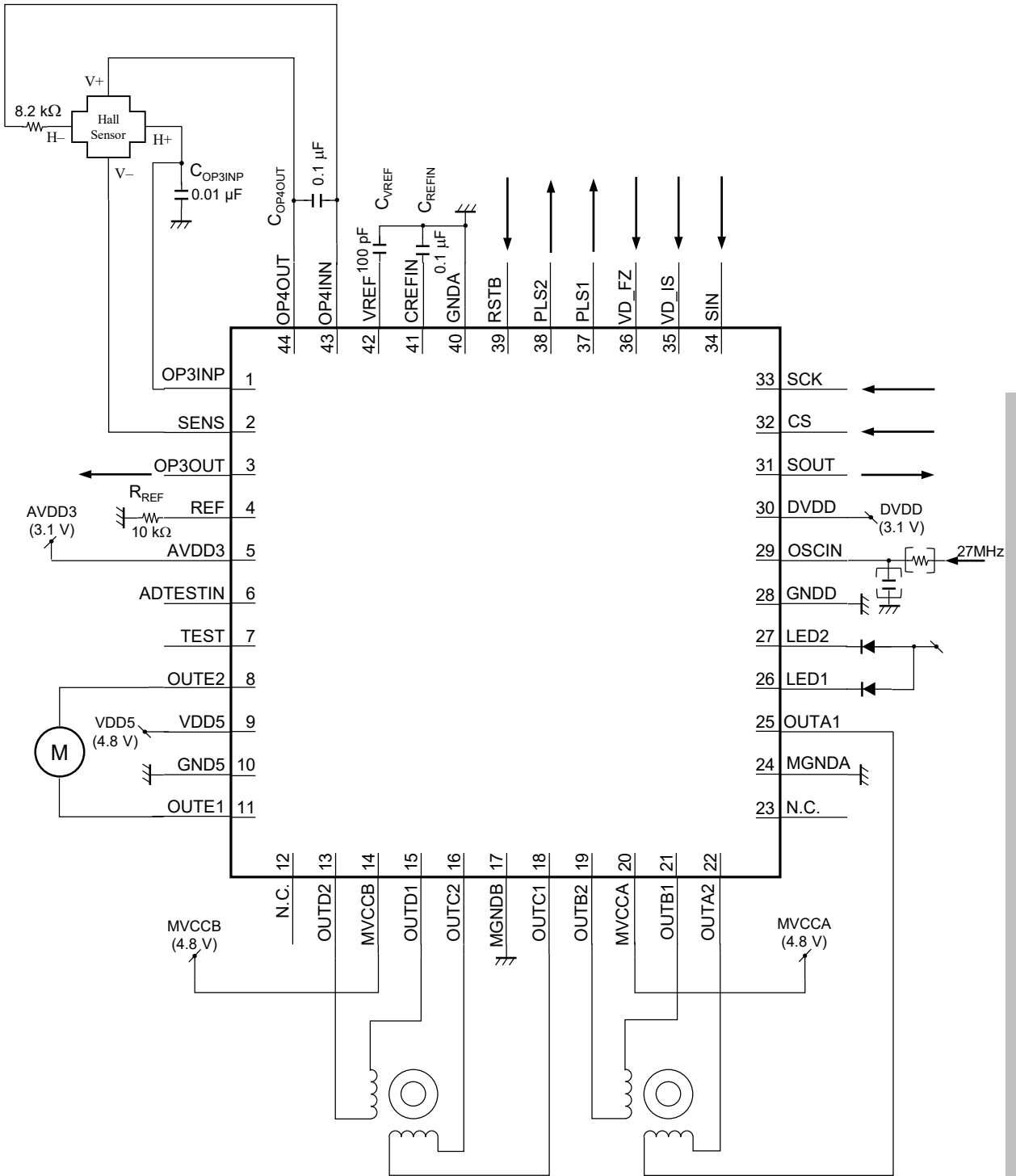
low acoustic noise microstep drive.



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Application Circuit Example



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Note) This application circuit is shown as an example but does not guarantee the design for mass production set.

**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Rating	Unit	Note
Controller supply voltage	AVDD3	-0.3 to + 4.0	V	*1
	DVDD	-0.3 to + 4.0		
Supply voltage for motor controller 1	MVCCA, MVCCB	-0.3 to + 6.0	V	*1
Supply voltage for motor controller 2	VDD5	-0.3 to + 6.0	V	*1
Operating ambient temperature	T <sub>opr</sub>	-40 to + 105	°C	*2, *4
Operating junction temperature	T <sub>j</sub>	-40 to + 150	°C	*2
Storage temperature	T <sub>stg</sub>	-55 to + 150	°C	*2
Motor driver 1 H bridge drive current (DC current)	OUTA1, OUTA2, OUTB1, OUTB2, OUTC1, OUTC2, OUTD1, OUTD2	±0.25	A/ch	—
Motor driver 2 H bridge drive current (DC current)	OUTE1, OUTE2	±0.15	A/ch	—
Instantaneous H bridge drive current	I <sub>M(pulse)</sub>	±0.4	A/ch	—
Input Voltage Range	OP3INP, OP4INN, ADTESTIN, REF, CREFIN	-0.3 to (AVDD3 + 0.3)	V	*3
	TEST, OSCIN, CS, SCK, SIN, VD_IS, VD_FZ, RSTB	-0.3 to (DVDD + 0.3)	V	*3
Output Voltage Range	OP3OUT, OP4OUT, SENS,VREF	-0.3 to (AVDD3 + 0.3)	V	*3
	PLS1, PLS2, SOUT	-0.3 to (DVDD + 0.3)	V	*3
Output Current Range	LED1, LED2	30	mA	—
ESD	HBM (Human Body Model)	±2	kV	—

Notes). This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteed as it is higher than our stated recommended operating range. When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

- \*1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.
- \*2: Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for Ta = 25°C.
- \*3: (DVDD + 0.3 ) V must not be exceeded 4.0 V and (AVDD + 0.3 ) V must not be exceeded 4.0 V.
- \*4: When using this IC, refer to the PD-Ta diagram of the package information and design the heat radiation with sufficient margin so that the allowable value might not be exceeded based on the conditions of power supply voltage, load, and ambient temperature.

## POWER DISSIPATION RATING

Condition	$\theta_{JA}$	PD (Ta=25 °C)	PD (Ta=105 °C)
Mount on PWB *1	54.2°C/W	2.303W	0.829W

Note). For the actual usage, follow the power supply voltage, load and ambient temperature conditions to ensure that there is enough margin and the thermal design does not exceed the allowable value.

\*1: Glass-Epoxy: 50 × 50 × 0.8 (mm), Die-pad joint



### CAUTION

Although this has limited built-in ESD protection circuit, but permanent damage may occur on it. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Supply voltage range	AVDD3, DVDD	2.7	3.1	3.6	V	*1
	MVCCA, MVCCB, VDD5	3.0	4.8	5.5	V	*1
Input Voltage Range	OP3INP, OP4INN, ADTESTIN, REF, CREFIN	-0.3	—	AVDD3 + 0.3	V	*2
	TEST, OSCIN, CS, SCK, SIN, VD_IS, VD_FZ, RSTB	-0.3	—	DVDD + 0.3	V	*2
Output Voltage Range	OP3OUT, OP4OUT, SENS, VREF	-0.3	—	AVDD3 + 0.3	V	*2
	PLS1, PLS2, SOUT	-0.3	—	DVDD + 0.3	V	*2
Output Current Range	OUTA1, OUTA2, OUTB1, OUTB2, OUTC1, OUTC2, OUTD1, OUTD2	-0.25	—	0.25	A	*1
	OUTE1, OUTE2	-0.15	—	0.15	A	*1
	LED1, LED2	—	—	30	mA	*1
External Constants	C <sub>VREF</sub>		100		pF	—
	C <sub>REFIN</sub>		0.1		μF	—
	R <sub>REF</sub>		10		kΩ	—
	C <sub>OP3INP</sub>		0.01		μF	—
	C <sub>OP4OUT</sub>		0.1		μF	—
Operating ambient temperature	Ta <sub>opr</sub>	-40		105	°C	—

Note) \*1 : It is a value under the conditions which do not exceed the absolute maximum rating and the power dissipation.

\*2 : (DVDD + 0.3 ) V must not be exceeded 4.0 V and (AVDD + 0.3 ) V must not be exceeded 4.0 V.

**ELECTRICAL CHARACTERISTICS**

VDD5 = MVCCx = 4.8 V, DVDD = AVDD3 = 3.1 V      T<sub>a</sub> = 25°C±2°C

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>Current circuit, Common circuit</b>							
MVCC supply current on Reset	I <sub>Omdisable</sub>	No load, no 27 MHz input	—	0	3.0	μA	
MVCC supply current on Enable	I <sub>menable</sub>	Output open	—	0.5	1.5	mA	
3 V supply current on Reset	I <sub>cc3_reset</sub>	No 27 MHz input	—	0	10.0	μA	
3 V supply current on Enable	I <sub>cc3_enable</sub>	Output open	—	7.0	20.0	mA	
VDD5 supply current on Reset	I <sub>cc5_reset</sub>	No 27 MHz input	—	0	3.0	μA	
VDD5 supply current on Enable	I <sub>cc5_enable</sub>	Output open	—	0.3	1.0	mA	
Supply current on Standby	I <sub>ccstandby</sub>	RSTB = High, output open, 27 MHz input, Total current	—	5.0	10.0	mA	
Supply current when FZ is Enable and Iris is in power save mode	I <sub>ccps</sub>	RSTB = High, output open, 27 MHz input, FZ = Enable, Total current	—	6.0	12.0	mA	
<b>Digital input / output</b>							
High-level input	V <sub>in(H)</sub>	RSTB	0.54 × DVDD	—	DVDD + 0.3	V	
Low-level input	V <sub>in(L)</sub>	RSTB	-0.3	—	0.2 × DVDD	V	
SOUT High-level output	V <sub>out(H) : SDATA</sub>	[SOUT] 1 mA Source	DVDD - 0.5	—	—	V	
SOUT Low-level output	V <sub>out(L) : SDATA</sub>	[SOUT] 1 mA Sink	—	—	0.5	V	
PLS1 to 2 High-level output	V <sub>out(H) : MUX</sub>	—	0.9 × DVDD	—	—	V	
PLS1 to 2 Low-level output	V <sub>out(L) : MUX</sub>	—	—	—	0.1 × DVDD	V	
Input pull-down resistance	R <sub>pullret</sub>	RSTB	50	100	200	kΩ	
<b>Motor driver 1</b>							
H bridge ON resistance	R <sub>onFZ</sub>	IM = 100 mA (Upper+Lower)	—	—	2.5	Ω	
H bridge leak current	I <sub>leakFZ</sub>	—	—	—	0.8	μA	
<b>Motor driver 2</b>							
H bridge ON resistance	R <sub>onIR</sub>	IM = 50 mA (Upper+Lower)	—	—	5	Ω	
H bridge leak current	I <sub>leakIR</sub>	—	—	—	0.8	μA	
<b>LED driver</b>							
Output ON resistance	R <sub>onLED</sub>	I = 20 mA, 5 V cell	—	—	8	Ω	
Output leak current	I <sub>leakLED</sub>	—	—	—	0.8	μA	



**ELECTRICAL CHARACTERISTICS (continued)**

VDD5 = MVCCx = 4.8 V, DVDD = AVDD3 = 3.1 V T<sub>a</sub> = 25°C±2°C

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>OPAMP3 (HALL Sensor Amp. for output amplifier)</b>							
Input voltage range	V <sub>IN</sub>	—	$\frac{1}{2}$ AVDD3 - 0.5	$\frac{1}{2}$ AVDD3	$\frac{1}{2}$ AVDD3 + 0.5	V	
Input offset voltage	V <sub>OF</sub>	—	-15	—	15	mV	
Output voltage (Low)	V <sub>OL</sub>	I = 100 $\mu$ A Sink	—	0.1	0.2	V	
Output voltage (High)	V <sub>OH</sub>	I = 100 $\mu$ A Source	AVDD3 - 0.2	AVDD3 - 0.1	—	V	
Gain	V <sub>OG</sub>	Gain setting value : 0h	19.7	21.9	24.1	V/V	
<b>OPAMP4 (HALL Sensor Amp. for eliminating common-mode voltage)</b>							
Input voltage range	V <sub>IN</sub>	—	$\frac{1}{2}$ AVDD3 - 0.1	—	$\frac{1}{2}$ AVDD3 + 0.1	V	
Input offset voltage	V <sub>OF</sub>	—	-10	—	10	mV	
Output voltage (Low)	V <sub>OL</sub>	I = 10 $\mu$ A Sink	—	0.1	0.2	V	
Output voltage (High)	V <sub>OH</sub>	I = 3 mA Source	AVDD3 - 0.5	AVDD3 - 0.2	—	V	
<b>Reference voltage output block</b>							
Output voltage 1	VREF	I = 0 A, CVREF = 100 pF	$\frac{1}{2}$ AVDD3 - 0.1	$\frac{1}{2}$ AVDD3	$\frac{1}{2}$ AVDD3 + 0.1	V	
Output voltage 2	VREFL	I = $\pm$ 100 $\mu$ A, CVREF = 100 pF	VREF - 0.1	VREF	VREF + 0.1	V	
<b>Hall bias controller (SENS pin output)</b>							
Min. output current	IBL	REF = 10 k $\Omega$ , SENS = 0.7 V Setting value : 00 h	—	0	0.1	mA	
Output current accuracy 1	IB40H	REF = 10 k $\Omega$ , SENS = 0.7 V Setting value : 40 h	0.9	1.02	1.14	mA	
Output current accuracy 2	IBBFH	REF = 10 k $\Omega$ , SENS = 0.7 V Setting value : BE h	2.66	3.02	3.38	mA	

**ELECTRICAL CHARACTERISTICS (continued)**

VDD5 = MVCCx = 4.8 V, DVDD = AVDD3 = 3.1 V T<sub>a</sub> = 25°C±2°C

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>Serial port input</b>							
Serial clock	Sclock	—	1	—	5	MHz	*1
SCK low time	T1	—	100	—	—	ns	*1
SCK high time	T2	—	100	—	—	ns	*1
CS setup time	T3	—	60	—	—	ns	*1
CS hold time	T4	—	60	—	—	ns	*1
CS disable high time	T5	—	100	—	—	ns	*1
SIN setup time	T6	—	50	—	—	ns	*1
SIN hold time	T7	—	50	—	—	ns	*1
SOUT delay time	T8	—	—	—	60	ns	*1
SOUT hold time	T9	—	60	—	—	ns	*1
SOUT Enable-Hi-Z time	T10	—	—	—	60	ns	*1
SOUT Hi-Z-Enable time	T11	—	—	—	60	ns	*1
SOUT C load	T <sub>SC</sub>	—	—	—	40	pF	*1
<b>Digital input / output</b>							
High-level input threshold voltage	V <sub>in(H)</sub>	SCK, SIN, CS, OSCIN, VD_IS, VD_FZ, TEST	—	1.36	—	V	*1
Low-level input threshold voltage	V <sub>in(L)</sub>	SCK, SIN, CS, OSCIN, VD_IS, VD_FZ, TEST	—	1.02	—	V	*1
RSTB signal pulse width	Trst	—	100	—	—	μs	*1
Input hysteresis width	V <sub>hysin</sub>	SCK, SIN, CS, OSCIN, VD_IS, VD_FZ, TEST	—	0.34	—	V	*1
Video sync. signal width	VD <sub>W</sub>	—	80	—	—	μs	*1
CS signal wait time 1	T <sub>(VD-CS)</sub>	—	400	—	—	ns	*1
CS signal wait time 2	T <sub>(CS-DT1)</sub>	—	5	—	—	μs	*1

Note) \*1 : Typical Design Value..

**ELECTRICAL CHARACTERISTICS (continued)**

VDD5 = MVCCx = 4.8 V, DVDD = AVDD3 = 3.1 V  $T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>Pulse generator</b>							
Pulse start resolution for pulse 1	PL1wait	OSCIN = 27 MHz	—	20.1	—	$\mu\text{s}$	*1
Pulse resolution for pulse 1	PL1width	OSCIN = 27 MHz	—	1.2	—	$\mu\text{s}$	*1
Pulse start resolution for pulse 2	PL2wait	OSCIN = 27 MHz	—	20.1	—	$\mu\text{s}$	*1
<b>Iris control</b>							
AD sampling frequency	IRIS <sub>Sample</sub>	OSCIN = 27 MHz	—	500	—	kHz	*1
<b>Thermal shutdown</b>							
Thermal shutdown operation temperature	T <sub>tsd</sub>	—	—	150	—	$^{\circ}\text{C}$	*1
Thermal shutdown hysteresis width	$\Delta$ T <sub>tsd</sub>	—	—	40	—	$^{\circ}\text{C}$	*1
<b>Supply voltage monitor circuit</b>							
3.3 V Reset operation	V <sub>rston</sub>	—	—	2.27	—	V	*1
3.3 V Reset hysteresis width	V <sub>rsthys</sub>	—	—	0.2	—	V	*1
MVCCx Reset operation	V <sub>rstFZon</sub>	—	—	2.2	—	V	*1
MVCCx Reset hysteresis width	V <sub>rstFZhys</sub>	—	—	0.2	—	V	*1
VDD5 Reset operation	V <sub>rstlSon</sub>	—	—	2.2	—	V	*1
VDD5 Reset hysteresis width	V <sub>rstlShys</sub>	—	—	0.2	—	V	*1
<b>8 bit DAC for Hall Offset adjustment</b>							
Adjustment range (High)	DAOTHof	—	—	AVDD <sub>3</sub>	—	V	*1
Adjustment range (Low)	DAOTLof	—	—	0	—	V	*1
<b>10 bit ADC</b>							
Input Range (High)	V <sub>in(H)</sub>	—	—	—	AVDD <sub>3-0.2</sub>	V	*1
Input Range (Low)	V <sub>in(L)</sub>	—	0.2	—	—	V	*1
DNLE (Differential linearity error)	DNL10A	—	—	1.0	—	LSB	*1
INLE (Integral linearity error)	INL10A	—	—	2.0	—	LSB	*1

Note) \*1 : Typical Design Value.

**PIN DESCRIPTIONS**

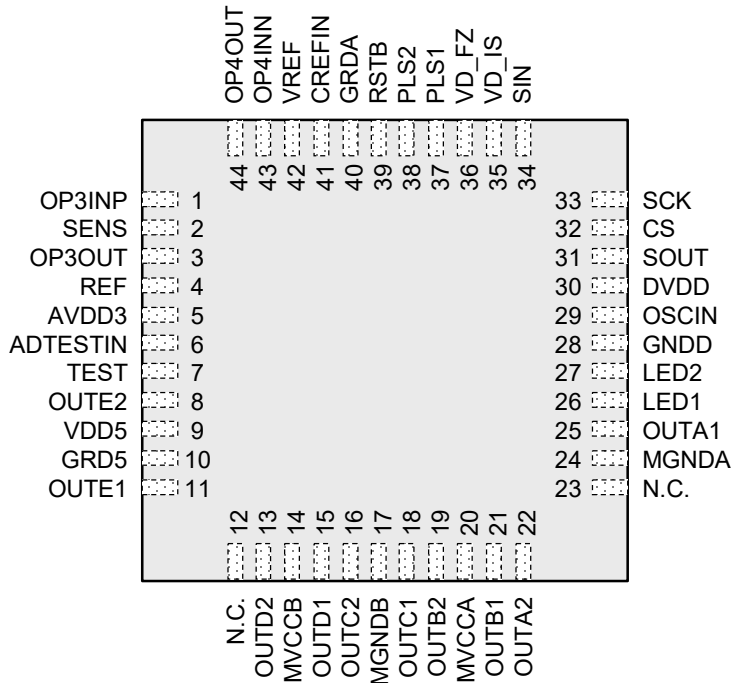
Pin No.	Pin name	Type	Description
1	OP3INP	Input	Hall signal amplifier non-inverting input
2	SENS	Output	Hall current bias output
3	OP3OUT	Output	Hall signal amplifier output
4	REF	—	Resistor connection for Hall current bias setting
5	AVDD3	Power supply	3 V analog power supply
6	ADTESTIN	Input	ADC test input
7	TEST	Input	Test mode input
8	OUTE2	Output	Motor output E2
9	VDD5	Power supply	Power supply for Iris
10	GND5	Ground	GND for Iris
11	OUTE1	Output	Motor output E1
12, 23	N. C.	—	N. C.
13	OUTD2	Output	Motor output D2
14	MVCCB	Power supply	Power supply for motor B
15	OUTD1	Output	Motor output D1
16	OUTC2	Output	Motor output C2
17	MGNDB	Ground	GND for motor B
18	OUTC1	Output	Motor output C1
19	OUTB2	Output	Motor output B2
20	MVCCA	Power supply	Power supply for motor A
21	OUTB1	Output	Motor output B1
22	OUTA2	Output	Motor output A2
24	MGNDA	Ground	GND for motor A
25	OUTA1	Output	Motor output A1
26	LED1	Input	Open-drain 1 for driving LED
27	LED2	Input	Open-drain 2 for driving LED
28	GNDD	Ground	Digital GND
29	OSCIN	Input	OSCIN input. 27MHz signal input recommended.
30	DVDD	Power supply	3 V digital power supply
31	SOUT	Output	Serial data output
32	CS	Input	Chip select signal input
33	SCK	Input	Serial clock input

**PIN DESCRIPTIONS (Continued)**

Pin No.	Pin name	Type	Description
34	SIN	Input	Serial data input
35	VD_IS	Input	Iris video sync. signal input
36	VD_FZ	Input	Focus zoom sync. signal input
37	PLS1	Output	Pulse 1 output
38	PLS2	Output	Pulse 2 output
39	RSTB	Input	Reset signal input
40	GNDA	Ground	3 V analog GND
41	CREFIN	—	(AVDD3)/2 capacitor connection pin
42	VREF	Output	Reference voltage for Hall sensor
43	OP4INN	Input	Midpoint bias amplifier inverting input
44	OP4OUT	Output	Midpoint bias amplifier output

**PIN CONFIGURATION**

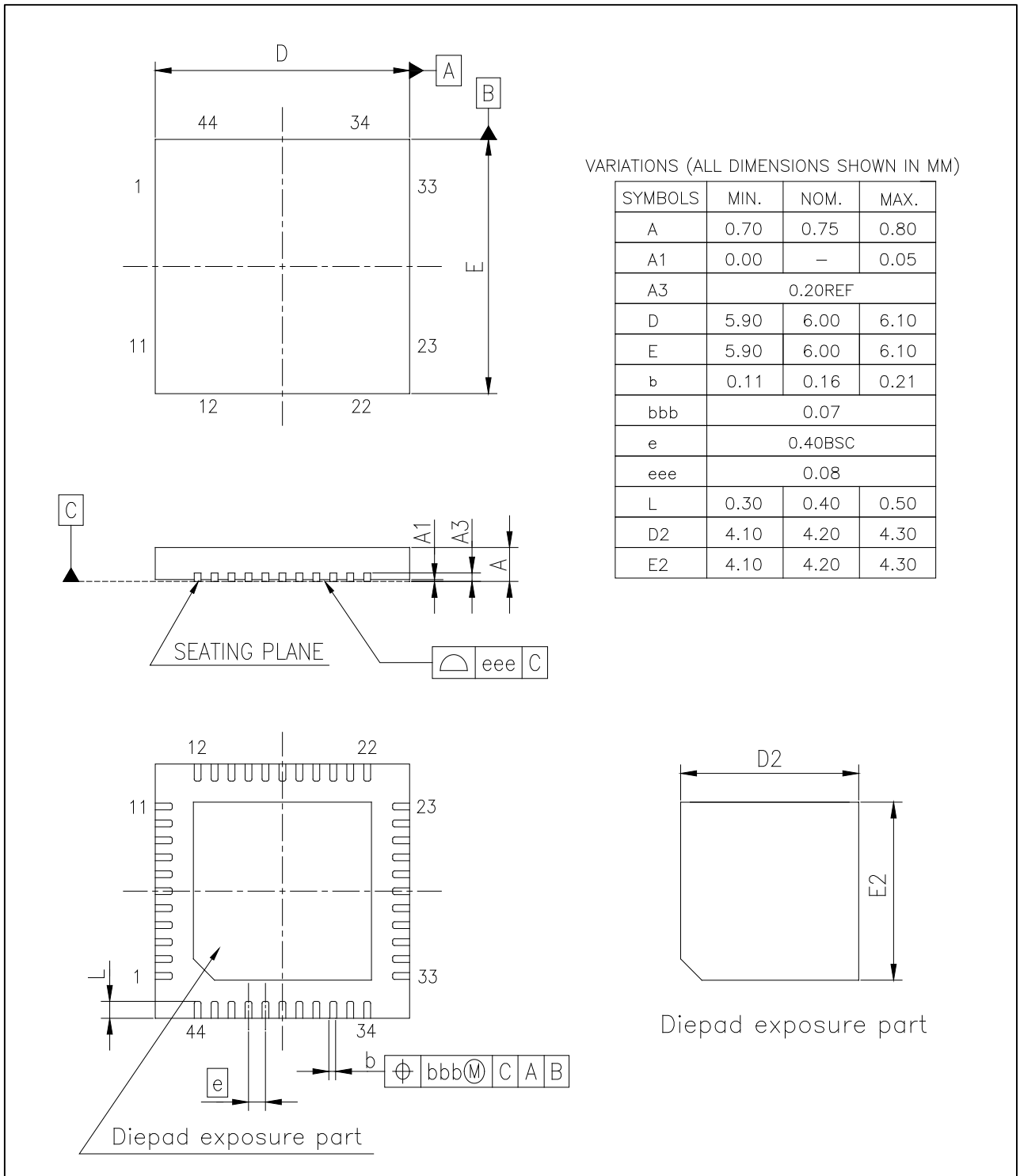
Top View



PACKAGE INFORMATION

Outline Drawing

QFN 44L 6x6mm<sup>2</sup>, Thickness 0.80mm, Lead Pitch 0.4mm,  
Lead Length 0.4mm, EP Size 4.2x4.2mm<sup>2</sup>



KA41908B Product Brief

**USAGE NOTES**

1. The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date datasheet in advance to make sure that the latest specifications satisfy your requirements.
2. The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products. No license is granted in and to any intellectual property right or other right owned by Nuvoton Technology Corporation Japan or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information de-scribed in this book.
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4. If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
5. When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.

Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

6. Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
7. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
8. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
9. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
10. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short) .

And, safety measures such as an installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.

11. The protection circuit is for maintaining safety against abnormal operation. Therefore, the protection circuit should not work during normal operation.

Especially for the thermal protection circuit, if the area of safe operation or the absolute maximum rating is momentarily exceeded due to output pin to VCC short (Power supply fault), or output pin to GND short (Ground fault), the LSI might be damaged before the thermal protection circuit could operate.

**USAGE NOTES (Continued)**

- 12. Unless specified in the product specifications, make sure that negative voltage or excessive voltage are not applied to the pins because the device might be damaged, which could happen due to negative voltage or excessive voltage generated during the ON and OFF timing when the inductive load of a motor coil or actuator coils of optical pick-up is being driven.
- 13. The product which has specified ASO (Area of Safe Operation) should be operated in ASO
- 14. Verify the risks which might be caused by the malfunctions of external components.
- 15. Take time to check the characteristics on use. When changing an external circuit constant for use, consider not only static characteristics, but also transient characteristics and external parts with respect to the characteristics difference among ICs so that you can get enough margin. Moreover, consider the influence of electric charge remaining in an external capacitor on rising/falling of power supply.
- 16. Apply voltage from a low-impedance to power supply pins and connect a bypass capacitor to the LSI as near as possible.



**Revision History (Continued)**

Date	Revision	Description
2022.2.1	1.08	1. initially issued.

### Important Notice

**Nuvoton Products are neither intended nor warranted for usage in systems or equipment, any malfunction or failure of which may cause loss of human life, bodily injury or severe property damage. Such applications are deemed, "Insecure Usage".**

**Insecure usage includes, but is not limited to: equipment for surgical implementation, atomic energy control instruments, airplane or spaceship instruments, the control or operation of dynamic, brake or safety systems designed for vehicular use, traffic signal instruments, all types of safety devices, and other applications intended to support or sustain life.**

**All Insecure Usage shall be made at customer's risk, and in the event that third parties lay claims to Nuvoton as a result of customer's Insecure Usage, customer shall indemnify the damages and liabilities thus incurred by Nuvoton.**

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